IS61WV102416ALL
IS61WV102416BLL
IS64WV102416BLL

ISSI®

1M x 16 HIGH-SPEED ASYNCHRONOUS CMOS STATIC RAM WITH 3.3V SUPPLY

OCTOBER 2006

FEATURES

- High-speed access times:
  8, 10, 20 ns
- High-performance, low-power CMOS process
- Multiple center power and ground pins for greater noise immunity
- Easy memory expansion with $\overline{CE}$ and $\overline{OE}$ options
- $\overline{CE}$ power-down
- Fully static operation: no clock or refresh required
- TTL compatible inputs and outputs
- Single power supply
  V_{DD} 1.65V to 2.2V (IS61WV102416ALL)
  speed = 20ns for V_{DD} 1.65V to 2.2V
  V_{DD} 2.4V to 3.6V (IS61/64WV102416BLL)
  speed = 10ns for V_{DD} 2.4V to 3.6V
  speed = 8ns for V_{DD} 3.3V $\pm$ 5%
- Packages available:
  – 48-ball miniBGA (9mm x 11mm)
  – 48-pin TSOP (Type I)
- Industrial and Automotive Temperature Support
- Lead-free available
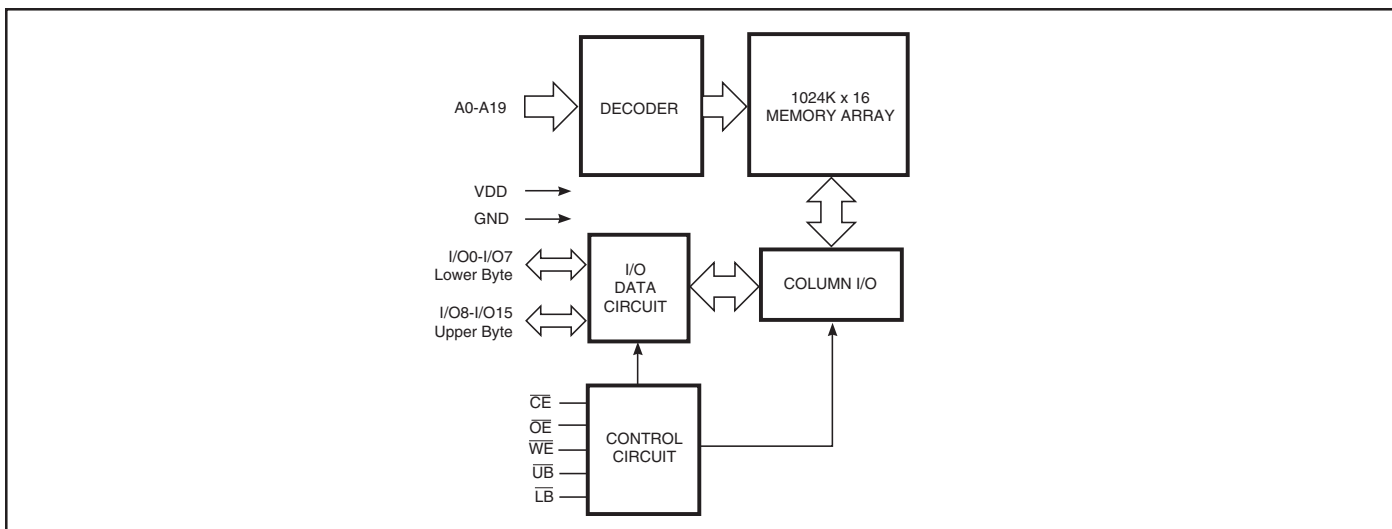- Data control for upper and lower bytes

DESCRIPTION

The *ISSI* IS61WV102416ALL/BLL and IS64WV102416BLL are high-speed, 16M-bit static RAMs organized as 1024K words by 16 bits. It is fabricated using *ISSI*'s high-performance CMOS technology. This highly reliable process coupled with innovative circuit design techniques, yields high-performance and low power consumption devices.

When $\overline{CE}$ is HIGH (deselected), the device assumes a standby mode at which the power dissipation can be reduced down with CMOS input levels.

Easy memory expansion is provided by using Chip Enable and Output Enable inputs, $\overline{CE}$ and $\overline{OE}$. The active LOW Write Enable ($\overline{WE}$) controls both writing and reading of the memory. A data byte allows Upper Byte ($\overline{UB}$) and Lower Byte ($\overline{LB}$) access.
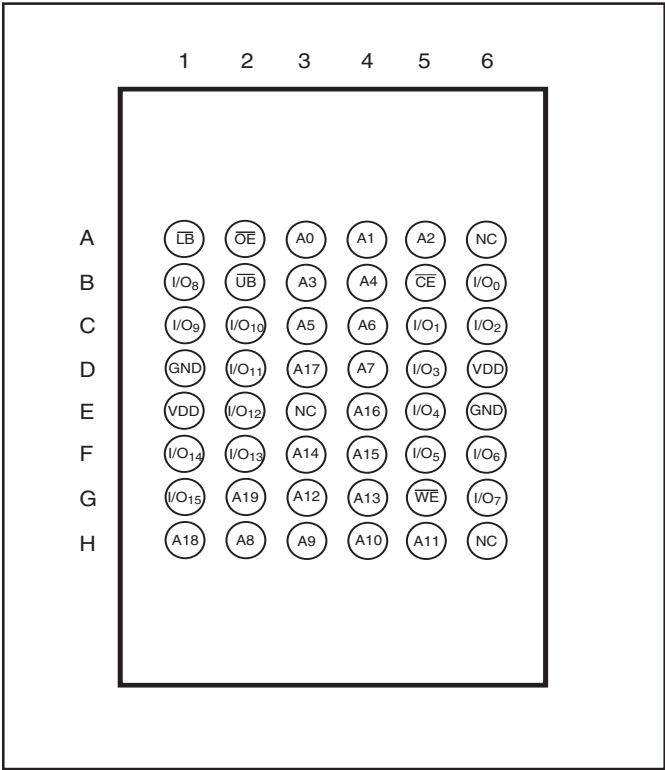
The device is packaged in the JEDEC standard 48-pin TSOP Type I and 48-pin Mini BGA (9mm x 11mm).

FUNCTIONAL BLOCK DIAGRAM

48-pin mini BGA (9mmx11mm)

	1	2	3	4	5	6
A	$\overline{LB}$	$\overline{OE}$	A0	A1	A2	NC
B	I/O$_8$	$\overline{UB}$	A3	A4	$\overline{CE}$	I/O$_0$
C	I/O$_9$	I/O$_{10}$	A5	A6	I/O$_1$	I/O$_2$
D	GND	I/O$_{11}$	A17	A7	I/O$_3$	VDD
E	VDD	I/O$_{12}$	NC	A16	I/O$_4$	GND
F	I/O$_{14}$	I/O$_{13}$	A14	A15	I/O$_5$	I/O$_6$
G	I/O$_{15}$	A19	A12	A13	$\overline{WE}$	I/O$_7$
H	A18	A8	A9	A10	A11	NC

PIN DESCRIPTIONS

A0-A19	Address Inputs
I/O0-I/O15	Data Inputs/Outputs
$\overline{CE}$	Chip Enable Input
$\overline{OE}$	Output Enable Input
$\overline{WE}$	Write Enable Input
$\overline{LB}$	Lower-byte Control (I/O0-I/O7)
$\overline{UB}$	Upper-byte Control (I/O8-I/O15)
NC	No Connection
V$_{DD}$	Power
GND	Ground

48-pin TSOP-I (12mm x 20mm)
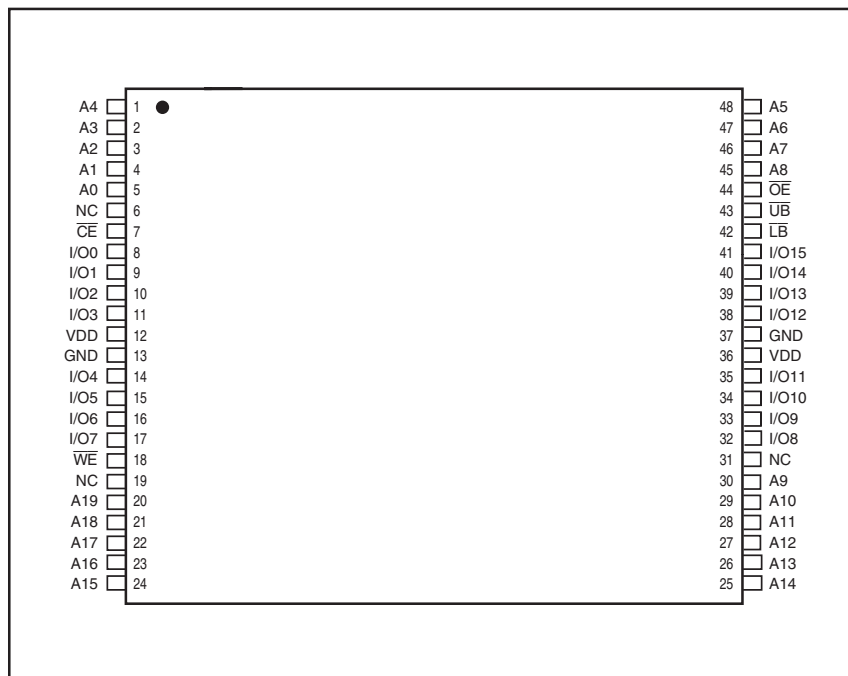
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A4  ┤ 1  ●          48 ├ A5
A3  ┤ 2             47 ├ A6
A2  ┤ 3             46 ├ A7
A1  ┤ 4             45 ├ A8
A0  ┤ 5             44 ├ OE
NC  ┤ 6             43 ├ UB
CE  ┤ 7             42 ├ LB
I/O0 ┤ 8            41 ├ I/O15
I/O1 ┤ 9            40 ├ I/O14
I/O2 ┤ 10           39 ├ I/O13
I/O3 ┤ 11           38 ├ I/O12
VDD ┤ 12            37 ├ GND
GND ┤ 13            36 ├ VDD
I/O4 ┤ 14           35 ├ I/O11
I/O5 ┤ 15           34 ├ I/O10
I/O6 ┤ 16           33 ├ I/O9
I/O7 ┤ 17           32 ├ I/O8
WE  ┤ 18            31 ├ NC
NC  ┤ 19            30 ├ A9
A19 ┤ 20            29 ├ A10
A18 ┤ 21            28 ├ A11
A17 ┤ 22            27 ├ A12
A16 ┤ 23            26 ├ A13
A15 ┤ 24            25 ├ A14
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PIN DESCRIPTIONS

A0-A19	Address Inputs
I/O0-I/O15	Data Inputs/Outputs
$\overline{CE}$	Chip Enable Input
$\overline{OE}$	Output Enable Input
$\overline{WE}$	Write Enable Input
$\overline{LB}$	Lower-byte Control (I/O0-I/O7)
$\overline{UB}$	Upper-byte Control (I/O8-I/O15)
NC	No Connection
V$_{DD}$	Power
GND	Ground

TRUTH TABLE

Mode	$\overline{WE}$	$\overline{CE}$	$\overline{OE}$	$\overline{LB}$	$\overline{UB}$	I/O PIN		V_{DD} Current
						I/O0-I/O7	I/O8-I/O15	
Not Selected	X	H	X	X	X	High-Z	High-Z	I_{SB1}, I_{SB2}
Output Disabled	H	L	H	X	X	High-Z	High-Z	I_{CC}
	X	L	X	H	H	High-Z	High-Z	
Read	H	L	L	L	H	D_{OUT}	High-Z	I_{CC}
	H	L	L	H	L	High-Z	D_{OUT}	
	H	L	L	L	L	D_{OUT}	D_{OUT}	
Write	L	L	X	L	H	D_{IN}	High-Z	I_{CC}
	L	L	X	H	L	High-Z	D_{IN}	
	L	L	X	L	L	D_{IN}	D_{IN}	

ABSOLUTE MAXIMUM RATINGS[1]

Symbol	Parameter	Value	Unit
V_{TERM}	Terminal Voltage with Respect to GND	−0.5 to V_{DD} + 0.5	V
V_{DD}	V_{DD} Relates to GND	−0.3 to 4.0	V
T_{STG}	Storage Temperature	−65 to +150	℃
P_T	Power Dissipation	1.0	W

Notes:
1. Stress greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

CAPACITANCE[1,2]

Symbol	Parameter	Conditions	Max.	Unit
C_{IN}	Input Capacitance	V_{IN} = 0V	6	pF
$C_{I/O}$	Input/Output Capacitance	V_{OUT} = 0V	8	pF

Notes:
1. Tested initially and after any design or process changes that may affect these parameters.
2. Test conditions: T_A = 25°C, f = 1 MHz, V_{DD} = 3.3V.

ISSI®

OPERATING RANGE (V$_{DD}$) (IS61WV102416ALL)

Range	Ambient Temperature	V$_{DD}$ (20 ns)
Commercial	0°C to +70°C	1.65V-2.2V
Industrial	−40°C to +85°C	1.65V-2.2V
Automotive	−40°C to +125°C	1.65V-2.2V

OPERATING RANGE (V$_{DD}$) (IS61WV102416BLL)[1]

Range	Ambient Temperature	V$_{DD}$ (8 ns)	V$_{DD}$ (10 ns)
Commercial	0°C to +70°C	3.3V ± 5%	2.4V-3.6V
Industrial	−40°C to +85°C	3.3V ± 5%	2.4V-3.6V

Note:
1. When operated in the range of 2.4V-3.6V, the device meets 10ns. When operated in the range of 3.3V ± 5%, the device meets 8ns.

OPERATING RANGE (V$_{DD}$) (IS64WV102416BLL)

Range	Ambient Temperature	V$_{DD}$ (10 ns)
Automotive	−40°C to +125°C	2.4V-3.6V

DC ELECTRICAL CHARACTERISTICS (Over Operating Range)

V_{DD} = 3.3V ± 5%

Symbol	Parameter	Test Conditions	Min.	Max.	Unit
V_{OH}	Output HIGH Voltage	V_{DD} = Min., I_{OH} = –4.0 mA	2.4	—	V
V_{OL}	Output LOW Voltage	V_{DD} = Min., I_{OL} = 8.0 mA	—	0.4	V
V_{IH}	Input HIGH Voltage		2	V_{DD} + 0.3	V
V_{IL}	Input LOW Voltage[1]		–0.3	0.8	V
I_{LI}	Input Leakage	GND ≤ V_{IN} ≤ V_{DD}	–1	1	µA
I_{LO}	Output Leakage	GND ≤ V_{OUT} ≤ V_{DD}, Outputs Disabled	–1	1	µA

Note:
1. V_{IL} (min.) = –0.3V DC; V_{IL} (min.) = –2.0V AC (pulse width - 2.0 ns). Not 100% tested.
   V_{IH} (max.) = V_{DD} + 0.3V DC; V_{IH} (max.) = V_{DD} + 2.0V AC (pulse width - 2.0 ns). Not 100% tested.

DC ELECTRICAL CHARACTERISTICS (Over Operating Range)

V_{DD} = 2.4V-3.6V

Symbol	Parameter	Test Conditions	Min.	Max.	Unit
V_{OH}	Output HIGH Voltage	V_{DD} = Min., I_{OH} = –1.0 mA	1.8	—	V
V_{OL}	Output LOW Voltage	V_{DD} = Min., I_{OL} = 1.0 mA	—	0.4	V
V_{IH}	Input HIGH Voltage		2.0	V_{DD} + 0.3	V
V_{IL}	Input LOW Voltage[1]		–0.3	0.8	V
I_{LI}	Input Leakage	GND ≤ V_{IN} ≤ V_{DD}	–1	1	µA
I_{LO}	Output Leakage	GND ≤ V_{OUT} ≤ V_{DD}, Outputs Disabled	–1	1	µA

Note:
1. V_{IL} (min.) = –0.3V DC; V_{IL} (min.) = –2.0V AC (pulse width - 2.0 ns). Not 100% tested.
   V_{IH} (max.) = V_{DD} + 0.3V DC; V_{IH} (max.) = V_{DD} + 2.0V AC (pulse width - 2.0 ns). Not 100% tested.

DC ELECTRICAL CHARACTERISTICS (Over Operating Range)

V_{DD} = 1.65V-2.2V

Symbol	Parameter	Test Conditions	V_{DD}	Min.	Max.	Unit
V_{OH}	Output HIGH Voltage	I_{OH} = -0.1 mA	1.65-2.2V	1.4	—	V
V_{OL}	Output LOW Voltage	I_{OL} = 0.1 mA	1.65-2.2V	—	0.2	V
V_{IH}	Input HIGH Voltage		1.65-2.2V	1.4	V_{DD} + 0.2	V
V_{IL}[1]	Input LOW Voltage		1.65-2.2V	–0.2	0.4	V
I_{LI}	Input Leakage	GND ≤ V_{IN} ≤ V_{DD}		–1	1	µA
I_{LO}	Output Leakage	GND ≤ V_{OUT} ≤ V_{DD}, Outputs Disabled		–1	1	µA

Notes:
1. V_{IL} (min.) = –0.3V DC; V_{IL} (min.) = –2.0V AC (pulse width - 2.0 ns). Not 100% tested.
   V_{IH} (max.) = V_{DD} + 0.3V DC; V_{IH} (max.) = V_{DD} + 2.0V AC (pulse width - 2.0 ns). Not 100% tested.

AC TEST CONDITIONS (HIGH SPEED)

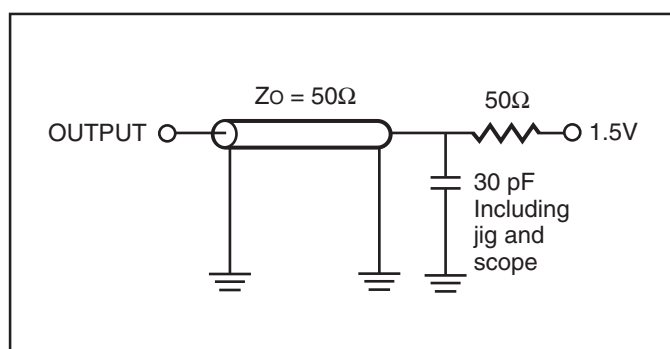| Parameter	Unit (2.4V-3.6V)	Unit (3.3V ± 5%)	Unit (1.65V-2.2V)
Input Pulse Level	0.4V to V_{DD}-0.3V	0.4V to V_{DD}-0.3V	0.4V to V_{DD}-0.2V
Input Rise and Fall Times	1.5ns	1.5ns	1.5ns
Input and Output Timing and Reference Level (V_{Ref})	V_{DD}/2	V_{DD}/2 + 0.05	V_{DD}/2
Output Load	See Figures 1 and 2	See Figures 1 and 2	See Figures 1 and 2

AC TEST LOADS

Figure 1.
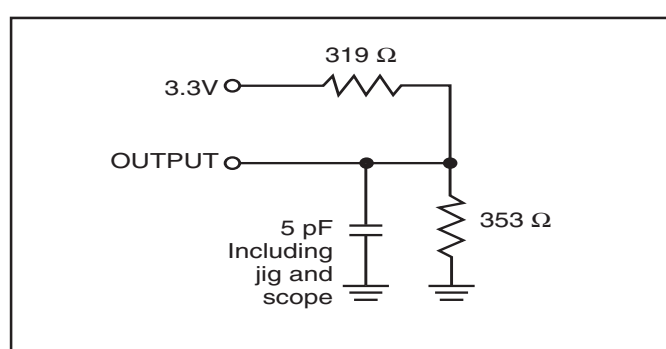
Figure 2.

POWER SUPPLY CHARACTERISTICS[1] (Over Operating Range)

Symbol	Parameter	Test Conditions		-8 Min.	-8 Max.	-10 Min.	-10 Max.	-20 Min.	-20 Max.	Unit
I_{CC}	V_{DD} Dynamic Operating Supply Current	V_{DD} = Max., I_{OUT} = 0 mA, f = f_{MAX} V_{IN} = 0.4V or V_{DD} –0.3V	Com. Ind. Auto. typ.[2]	— — —	110 115 —	— — — 60	90 95 140	— — —	50 60 100	mA
I_{CC1}	Operating Supply Current	V_{DD} = Max., I_{OUT} = 0 mA, f = 0 V_{IN} = 0.4V or V_{DD} –0.3V	Com. Ind. Auto.	— — —	85 90 —	— — —	85 90 110	— — —	45 55 90	mA
I_{SB1}	TTL Standby Current (TTL Inputs)	V_{DD} = Max., V_{IN} = V_{IH} or V_{IL} $\overline{CE} \geq V_{IH}$, f = 0	Com. Ind. Auto.	— — —	30 35 —	— — —	30 35 70	— — —	30 35 70	mA
I_{SB2}	CMOS Standby Current (CMOS Inputs)	V_{DD} = Max., $\overline{CE} \geq V_{DD}$ – 0.2V, $V_{IN} \geq V_{DD}$ – 0.2V, or $V_{IN} \leq$ 0.2V, f = 0	Com. Ind. Auto. typ.[2]	— — —	20 25 —	— — — 4	20 25 60	— — —	20 25 60	mA

Note:

1. At f = f_{MAX}, address and data inputs are cycling at the maximum frequency, f = 0 means no input lines change.

2. Typical values are measured at V_{DD} = 3.0V, T_A = 25°C and not 100% tested.

READ CYCLE SWITCHING CHARACTERISTICS[1] (Over Operating Range)

Symbol	Parameter	-8 Min.	-8 Max.	-10 Min.	-10 Max.	Unit
t_{RC}	Read Cycle Time	8	—	10	—	ns
t_{AA}	Address Access Time	—	8	—	10	ns
t_{OHA}	Output Hold Time	2.5	—	2.5	—	ns
t_{ACE}	$\overline{CE}$ Access Time	—	8	—	10	ns
t_{DOE}	$\overline{OE}$ Access Time	—	5.5	—	6.5	ns
t_{HZOE}[2]	$\overline{OE}$ to High-Z Output	—	3	—	4	ns
t_{LZOE}[2]	$\overline{OE}$ to Low-Z Output	0	—	0	—	ns
t_{HZCE}[2]	$\overline{CE}$ to High-Z Output	0	3	0	4	ns
t_{LZCE}[2]	$\overline{CE}$ to Low-Z Output	3	—	3	—	ns
t_{BA}	$\overline{LB}, \overline{UB}$ Access Time	—	5.5	—	6.5	ns
t_{HZB}[2]	$\overline{LB}, \overline{UB}$ to High-Z Output	0	3	0	3	ns
t_{LZB}[2]	$\overline{LB}, \overline{UB}$ to Low-Z Output	0	—	0	—	ns
t_{PU}	Power Up Time	0	—	0	—	ns
t_{PD}	Power Down Time	—	8	—	10	ns

Notes:

1. Test conditions assume signal transition times of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0V to 3.0V and output loading specified in Figure 1.
2. Tested with the load in Figure 2. Transition is measured ±500mV from steady-state voltage.

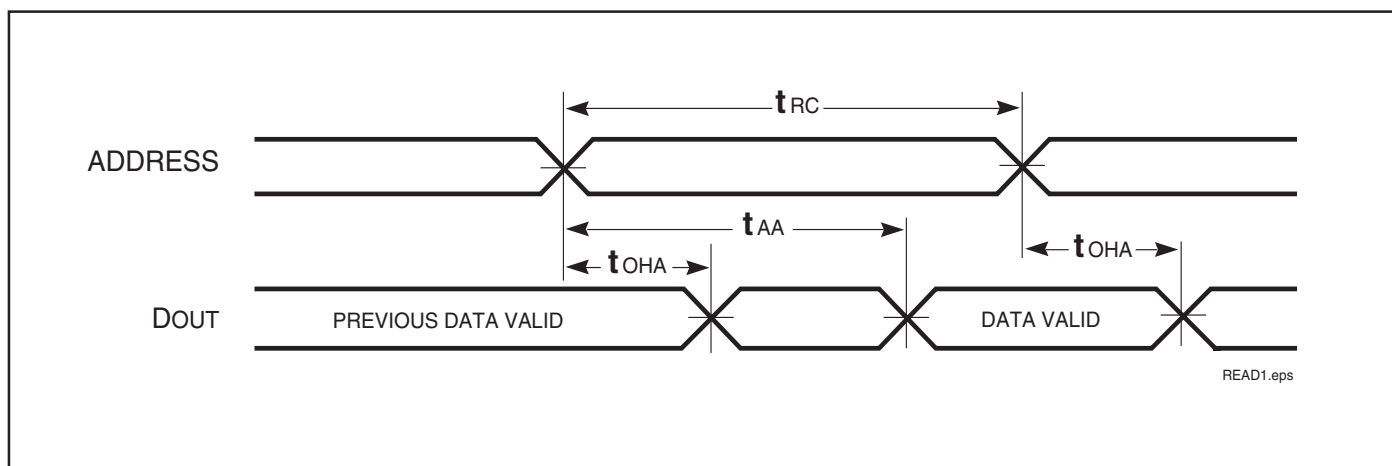## READ CYCLE SWITCHING CHARACTERISTICS[1] (Over Operating Range)

| Symbol	Parameter	-20 ns Min.	Max.	Unit
t_{RC}	Read Cycle Time	20	—	ns
t_{AA}	Address Access Time	—	20	ns
t_{OHA}	Output Hold Time	2.5	—	ns
t_{ACE}	$\overline{CE}$ Access Time	—	20	ns
t_{DOE}	$\overline{OE}$ Access Time	—	8	ns
t_{HZOE}[2]	$\overline{OE}$ to High-Z Output	0	8	ns
t_{LZOE}[2]	$\overline{OE}$ to Low-Z Output	0	—	ns
t_{HZCE}[2]	$\overline{CE}$ to High-Z Output	0	8	ns
t_{LZCE}[2]	$\overline{CE}$ to Low-Z Output	3	—	ns
t_{BA}	$\overline{LB}$, $\overline{UB}$ Access Time	—	8	ns
t_{HZB}	$\overline{LB}$, $\overline{UB}$ to High-Z Output	0	8	ns
t_{LZB}	$\overline{LB}$, $\overline{UB}$ to Low-Z Output	0	—	ns

Notes:
1. Test conditions assume signal transition times of 1.5 ns or less, timing reference levels of 1.25V, input pulse levels of 0.4V to V_{DD}-0.3V and output loading specified in Figure 1a.
2. Tested with the load in Figure 1b. Transition is measured ±500 mV from steady-state voltage. Not 100% tested.
3. Not 100% tested.

AC WAVEFORMS
READ CYCLE NO. 1[1,2] (Address Controlled) ($\overline{CE}$ = $\overline{OE}$ = V_{IL})

READ1.eps

READ CYCLE NO. 2[1,3] ($\overline{CE}$ and $\overline{OE}$ Controlled)

CE_RD2.eps
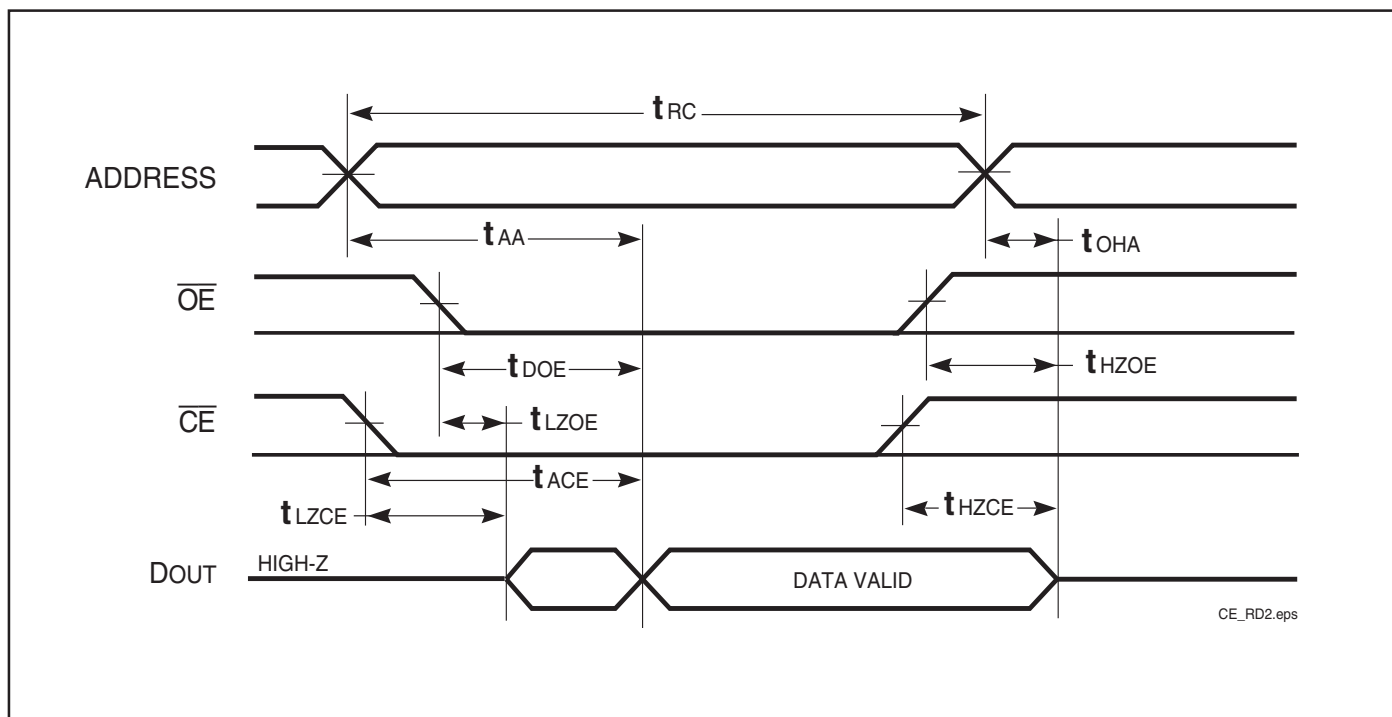
Notes:
1. $\overline{WE}$ is HIGH for a Read Cycle.
2. The device is continuously selected. $\overline{OE}$, $\overline{CE}$ = V_{IL}.
3. Address is valid prior to or coincident with $\overline{CE}$ LOW transitions.

WRITE CYCLE SWITCHING CHARACTERISTICS[1,3] (Over Operating Range)

Symbol	Parameter	-8 Min.	-8 Max.	-10 Min.	-10 Max.	Unit
t_{WC}	Write Cycle Time	8	—	10	—	ns
t_{SCE}	$\overline{CE}$ to Write End	6.5	—	8	—	ns
t_{AW}	Address Setup Time to Write End	6.5	—	8	—	ns
t_{HA}	Address Hold from Write End	0	—	0	—	ns
t_{SA}	Address Setup Time	0	—	0	—	ns
t_{PWB}	$\overline{LB}$, $\overline{UB}$ Valid to End of Write	6.5	—	8	—	ns
t_{PWE1}	$\overline{WE}$ Pulse Width	6.5	—	8	—	ns
t_{PWE2}	$\overline{WE}$ Pulse Width ($\overline{OE}$ = LOW)	8.0	—	10	—	ns
t_{SD}	Data Setup to Write End	5	—	6	—	ns
t_{HD}	Data Hold from Write End	0	—	0	—	ns
t_{HZWE}[2]	$\overline{WE}$ LOW to High-Z Output	—	3.5	—	5	ns
t_{LZWE}[2]	$\overline{WE}$ HIGH to Low-Z Output	2	—	2	—	ns

Notes:

1. Test conditions assume signal transition times of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0V to 3.0V and output loading specified in Figure 1.
2. Tested with the load in Figure 2. Transition is measured ±500 mV from steady-state voltage. Not 100% tested.
3. The internal write time is defined by the overlap of CE LOW and UB or LB, and WE LOW. All signals must be in valid states to initiate a Write, but any one can go inactive to terminate the Write. The Data Input Setup and Hold timing are referenced to the rising or falling edge of the signal that terminates the write. Shaded area product in development

## WRITE CYCLE SWITCHING CHARACTERISTICS[1,2] (Over Operating Range)

Symbol	Parameter	-20 ns		Unit
		Min.	Max.	
t_{WC}	Write Cycle Time	20	—	ns
t_{SCE}	$\overline{CE}$ to Write End	12	—	ns
t_{AW}	Address Setup Time to Write End	12	—	ns
t_{HA}	Address Hold from Write End	0	—	ns
t_{SA}	Address Setup Time	0	—	ns
t_{PWB}	$\overline{LB}$, $\overline{UB}$ Valid to End of Write	12	—	ns
t_{PWE1}	$\overline{WE}$ Pulse Width ($\overline{OE}$ = HIGH)	12	—	ns
t_{PWE2}	$\overline{WE}$ Pulse Width ($\overline{OE}$ = LOW)	17	—	ns
t_{SD}	Data Setup to Write End	9	—	ns
t_{HD}	Data Hold from Write End	0	—	ns
t_{HZWE}[3]	$\overline{WE}$ LOW to High-Z Output	—	9	ns
t_{LZWE}[3]	$\overline{WE}$ HIGH to Low-Z Output	3	—	ns

Notes:
1. Test conditions for IS61WV6416LL assume signal transition times of 1.5ns or less, timing reference levels of 1.25V, input pulse levels of 0.4V to V_{DD}-0.3V and output loading specified in Figure 1a.
2. Tested with the load in Figure 1b. Transition is measured ±500 mV from steady-state voltage. Not 100% tested.
3. The internal write time is defined by the overlap of $\overline{CE}$ LOW and $\overline{UB}$ or $\overline{LB}$, and $\overline{WE}$ LOW. All signals must be in valid states to initiate a Write, but any one can go inactive to terminate the Write. The Data Input Setup and Hold timing are referenced to the rising or falling edge of the signal that terminates the write.
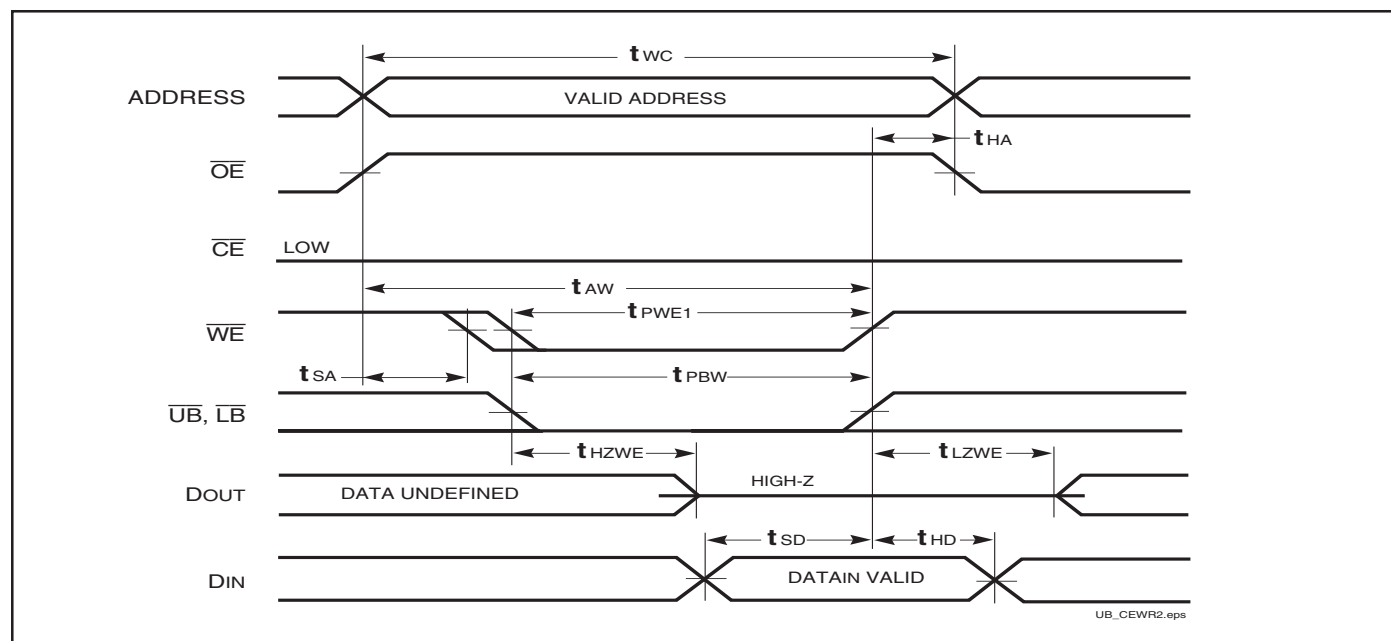
AC WAVEFORMS

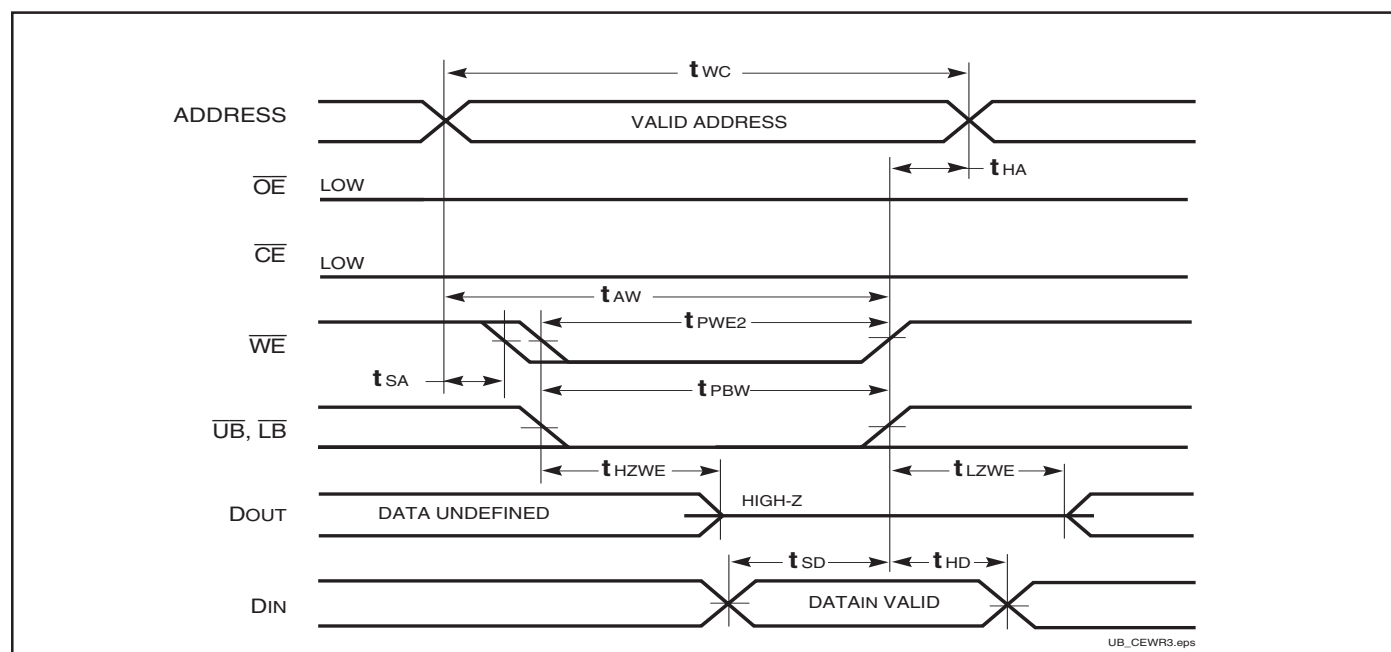## WRITE CYCLE NO. 1[1,2] ($\overline{CE}$ Controlled, $\overline{OE}$ = HIGH or LOW)

CE_WR1.eps
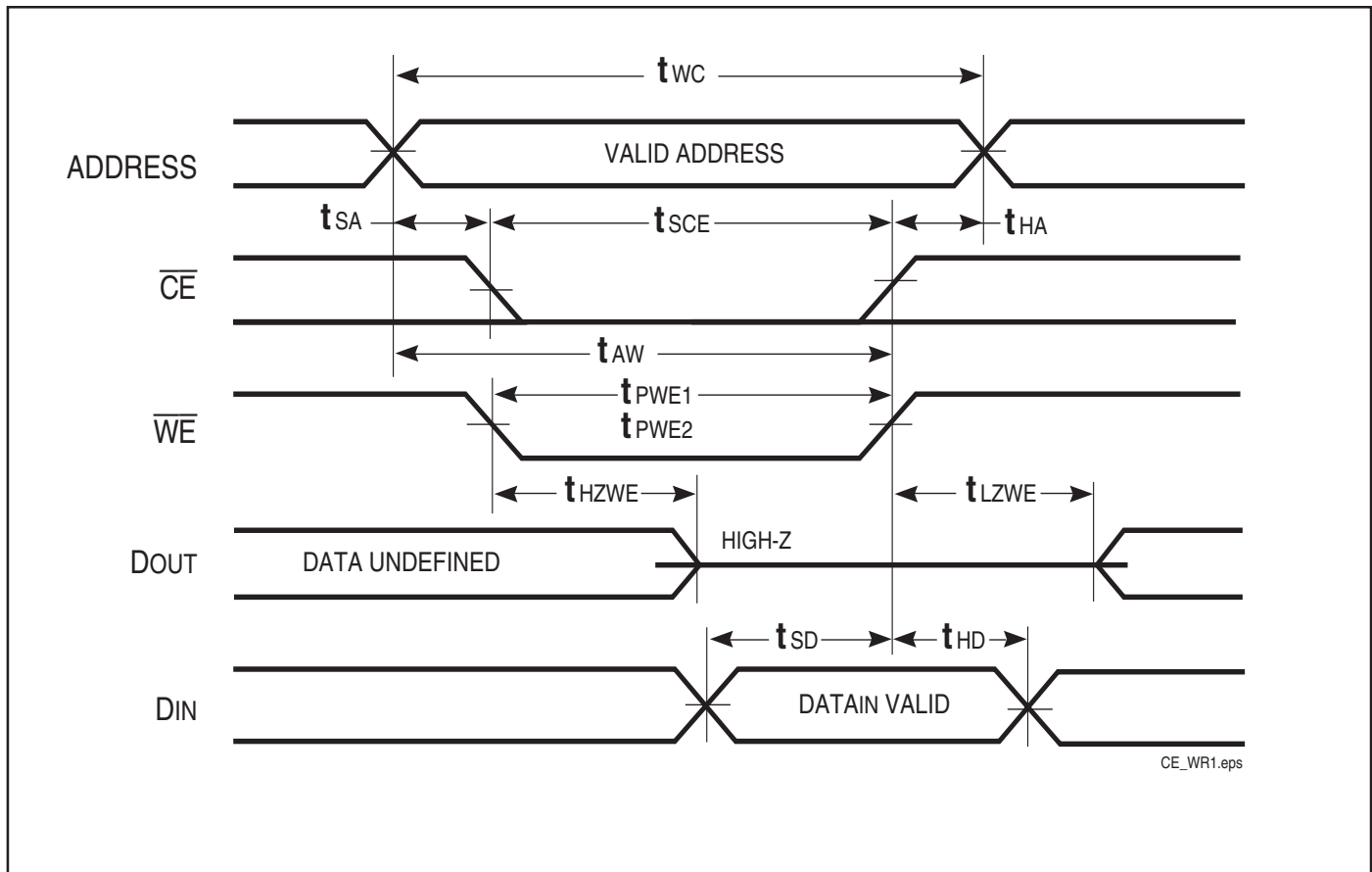
AC WAVEFORMS

WRITE CYCLE NO. 2 ($\overline{WE}$ Controlled. $\overline{OE}$ is HIGH During Write Cycle) [1,2]

UB_CEWR2.eps

WRITE CYCLE NO. 3 ($\overline{WE}$ Controlled. $\overline{OE}$ is LOW During Write Cycle) [1]

UB_CEWR3.eps

AC WAVEFORMS

### WRITE CYCLE NO. 4 ($\overline{LB}$, $\overline{UB}$ Controlled, Back-to-Back Write) [1,3]

UB_CEWR4.eps
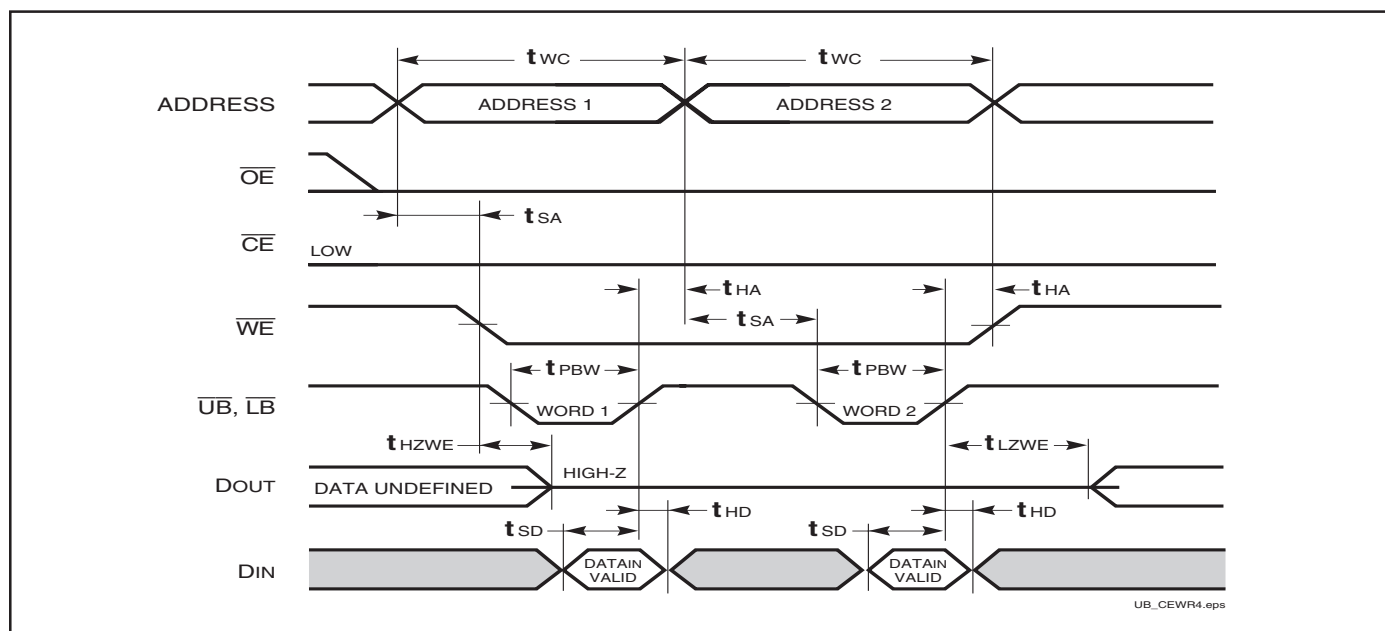
Notes:
1. The internal Write time is defined by the overlap of $\overline{CE}$ = LOW, $\overline{UB}$ and/or $\overline{LB}$ = LOW, and $\overline{WE}$ = LOW. All signals must be in valid states to initiate a Write, but any can be deasserted to terminate the Write. The t_{SA}, t_{HA}, t_{SD}, and t_{HD} timing is referenced to the rising or falling edge of the signal that terminates the Write.
2. Tested with $\overline{OE}$ HIGH for a minimum of 4 ns before $\overline{WE}$ = LOW to place the I/O in a HIGH-Z state.
3. $\overline{WE}$ may be held LOW across many address cycles and the $\overline{LB}$, $\overline{UB}$ pins can be used to control the Write function.

Rev. B
09/22/06

DATA RETENTION SWITCHING CHARACTERISTICS

Symbol	Parameter	Test Condition		Min.	Max.	Unit
V_{DR}	V_{DD} for Data Retention	See Data Retention Waveform		1.2	3.6	V
I_{DR}	Data Retention Current	$V_{DD} = 1.2V$, $\overline{CE} \geq V_{DD} - 0.2V$	Ind.	—	20	mA
			Auto.	—	50	
t_{SDR}	Data Retention Setup Time	See Data Retention Waveform		0	—	ns
t_{RDR}	Recovery Time	See Data Retention Waveform		t_{RC}	—	ns

DATA RETENTION WAVEFORM ($\overline{CE}$ Controlled)

ISSI®
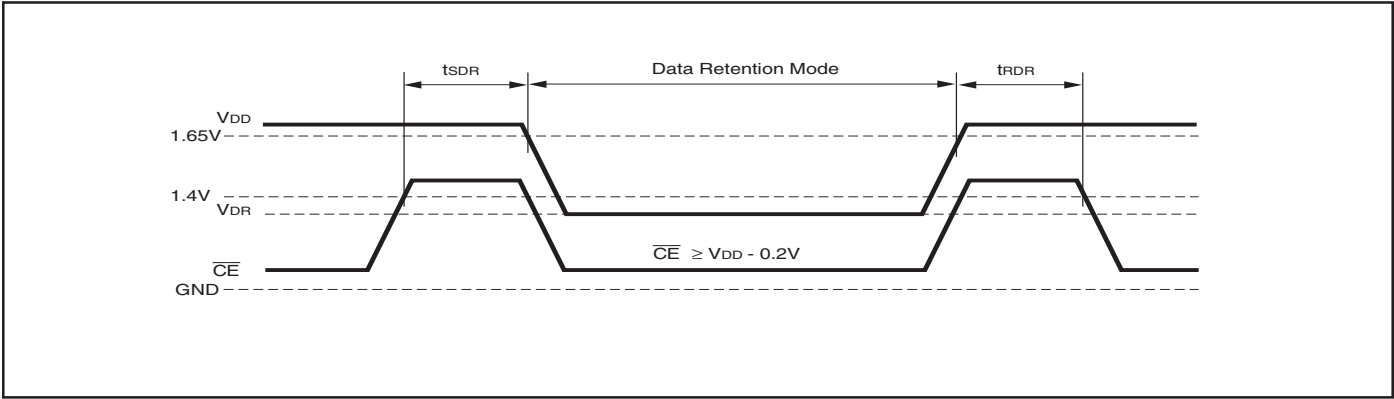
ORDERING INFORMATION

Industrial Range: -40°C to +85°C

Voltage Range: 2.4V to 3.6V

Speed (ns)	Order Part No.	Package
10 (8[1])	IS61WV102416BLL-10MI	48 mini BGA (9mm x 11mm)
	IS61WV102416BLL-10MLI	48 mini BGA (9mm x 11mm), Lead-free
	IS61WV102416BLL-10TI	TSOP (Type I)
	IS61WV102416BLL-10TLI	TSOP (Type I), Lead-free

Note:
1. Speed = 8ns for V_{DD} = 3.3V $\pm$ 5%. Speed = 10ns for V_{DD} = 2.4V - 3.6V

Industrial Range: -40°C to +85°C

Voltage Range: 1.65V to 2.2V

Speed (ns)	Order Part No.	Package
20	IS61WV102416ALL-20MI	48 mini BGA (9mm x 11mm)
	IS61WV102416ALL-20TI	TSOP (Type I)

Automotive Range: -40°C to +125°C

Voltage Range: 2.4V to 3.6V

Speed (ns)	Order Part No.	Package
10	IS64WV102416BLL-10MA3	48 mini BGA (9mm x 11mm)
	IS64WV102416BLL-10TA3	TSOP (Type I)

PACKAGING INFORMATION

ISSI®

Mini Ball Grid Array
Package Code: M (48-pin)

Top View

Bottom View

φ b (48x)

1 2 3 4 5 6

6 5 4 3 2 1

A
B
C
D
E
F
G
H

D

E

A2

A

A1

SEATING PLANE

e

D1

e

E1

A
B
C
D
E
F
G
H

Notes:
1. Controlling dimensions are in millimeters.

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Rev. D
01/15/03

PACKAGING INFORMATION

Mini Ball Grid Array
Package Code: M (48-pin)

mBGA - 6mm x 8mm

Sym.	MILLIMETERS Min.	Typ.	Max.	INCHES Min.	Typ.	Max.
N0. Leads		48				
A	—	—	1.20	.—	—	0.047
A1	0.25	—	0.40	0.010	—	0.016
A2	0.60	—	—	0.024	—	—
D	7.90	8.00	8.10	0.311	0.314	0.319
D1	5.60BSC			0.220BSC		
E	5.90	6.00	6.10	0.232	0.236	0.240
E1	4.00BSC			0.157BSC		
e	0.80BSC			0.031BSC		
b	0.40	0.45	0.50	0.016	0.018	0.020

mBGA - 7.2mm x 8.7mm

Sym.	MILLIMETERS Min.	Typ.	Max.	INCHES Min.	Typ.	Max.
N0. Leads		48				
A	—	—	1.20	—	—	0.047
A1	0 .24	—	0.30	0.009	—	0.012
A2	0.60	—	—	0.024	—	—
D	8.60	8.70	8.80	0.339	0.343	0.346
D1	5.25BSC			0.207BSC		
E	7.10	7.20	7.30	0.280	0.283	0.287
E1	3.75BSC			0.148BSC		
e	0.75BSC			0.030BSC		
b	0.30	0.35	0.40	0.012	0.014	0.016

mBGA - 9mm x 11mm

Sym.	MILLIMETERS Min.	Typ.	Max.	INCHES Min.	Typ.	Max.
N0. Leads		48				
A	—	—	1.20	—	—	0.047
A1	0.24	—	0.30	0.009	—	0.012
A2	0.60	—	—	0.024	—	—
D	10.90	11.00	11.10	0.429	0.433	0.437
D1	5.25BSC			0.207BSC		
E	8.90	9.00	9.10	0.350	0.354	0.358
E1	3.75BSC			0.148BSC		
e	0.75BSC			0.030BSC		
b	0.30	0.35	0.40	0.012	0.014	0.016

Plastic TSOP - 48 pins
Package Code: T (Type I)
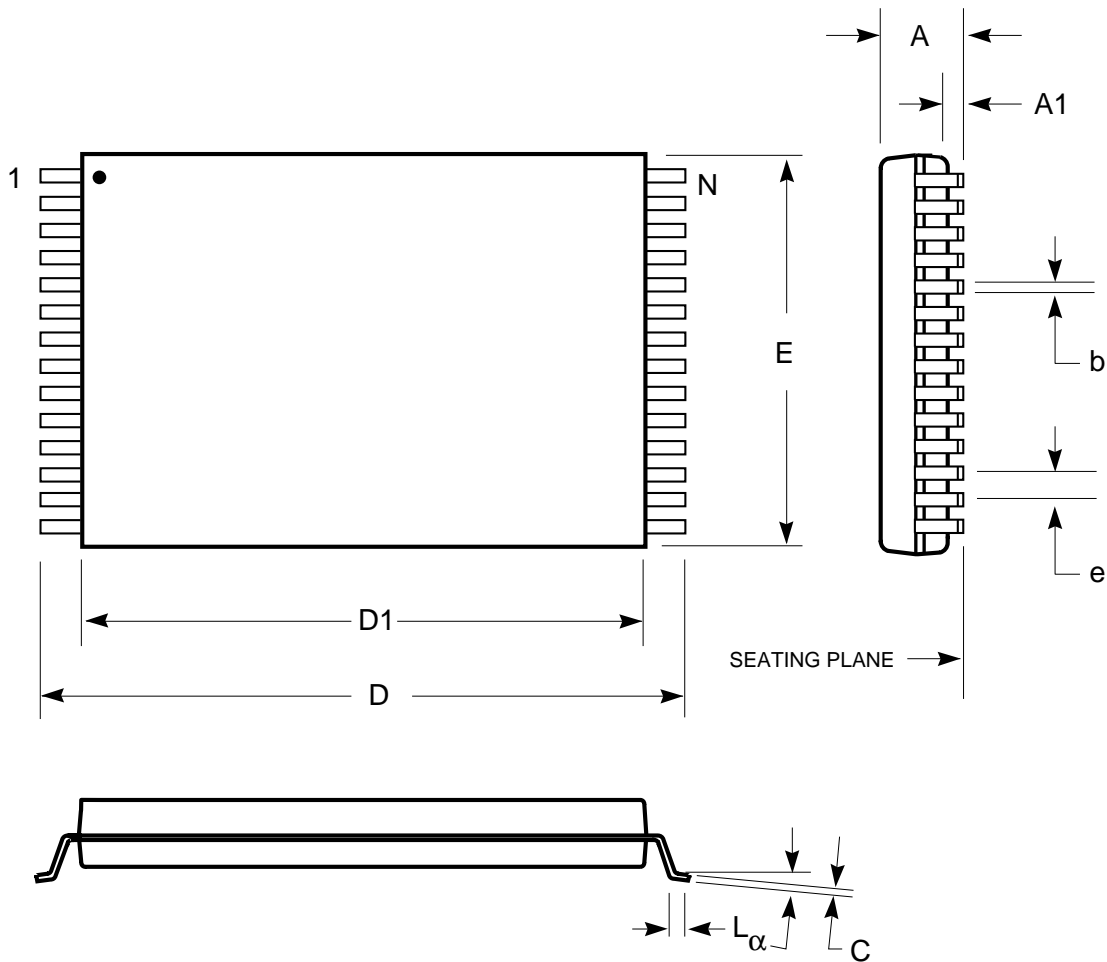
Plastic TSOP (T - Type I)				
	Millimeters		**Inches**	
Symbol	**Min**	**Max**	**Min**	**Max**
Ref. Std.				
N		48		
A	—	1.20	—	0.047
A1	0.05	0.15	0.002	0.006
b	0.17	0.27	0.007	0.011
C	0.10	0.21	0.004	0.008
D	19.8	20.2	0.780	0.795
D1	18.2	18.6	0.716	0.732
E	11.8	12.2	0.464	0.480
e	0.50 BSC		0.020 BSC	
L	0.50	0.70	0.020	0.028
α	0°	5°	0°	5°

Notes:
1. Controlling dimension: millimeters, unless otherwise specified.
2. BSC = Basic lead spacing between centers.
3. Dimensions D1 and E do not include mold flash protrusions and should be measured from the bottom of the package.
4. Formed leads shall be planar with respect to one another within 0.004 inches at the seating plane.